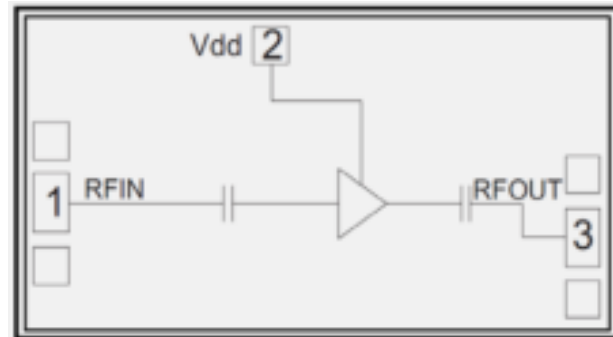


Features

- Frequency: 2.7-3.5GHz
- Small Signal Gain: 29dB
- Noise Figure: 0.6dB typ.
- Noise Figure: 0.65dB max.
- P1dB: 12dBm
- Power supply: +5V/50mA
- Input/Output: 50Ω
- Die Size: 2.0 x 1.3 x 0.1 mm

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

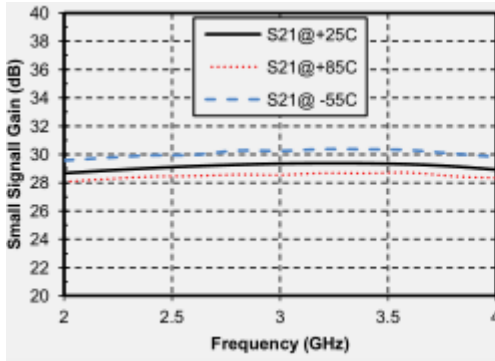
Functional Block Diagram

Electrical Specifications

TA = +25°C, Vd = +5V

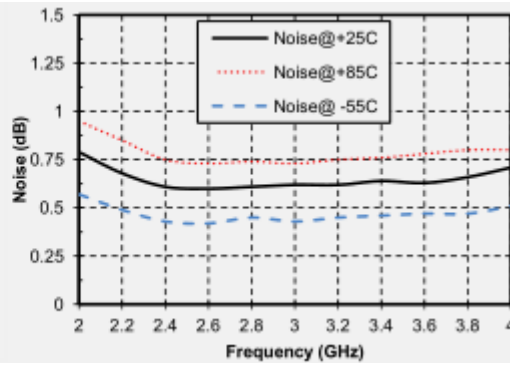
Parameters	Min.	Typ.	Max.	Units
Frequency	2.7-3.5			GHz
Small Signal Gain	28.5	29	29.5	dB
Gain Flatness	±0.5			dB
Noise Figure	-	0.6	0.65	dB
Output 1dB Compression (P1dB)	11.5	12	-	dBm
Input Return Loss	16	20	-	dB
Output Return Loss	18	22	-	dB
Static current		50		mA



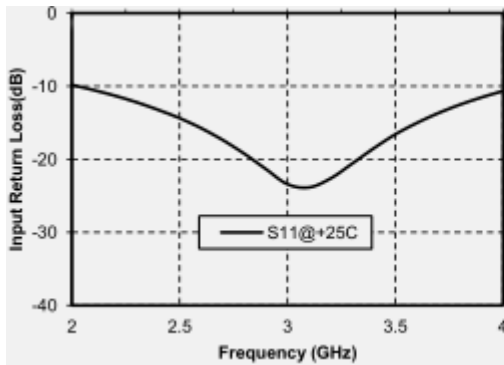
Gain vs. Frequency



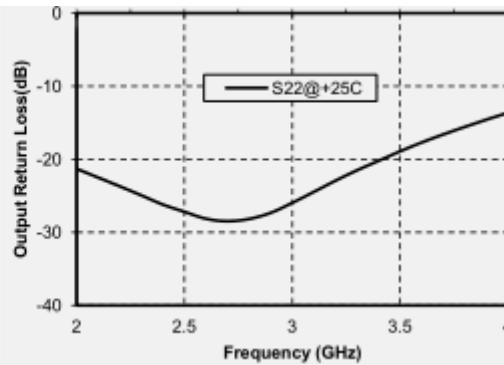
Noise Figure vs. Frequency



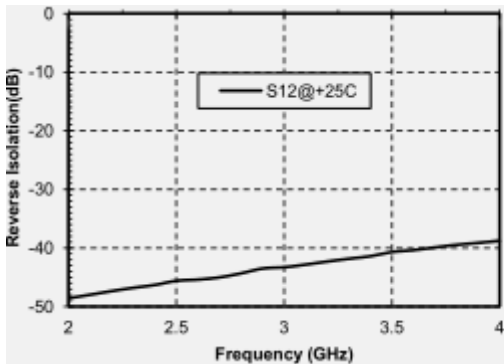
Input Return Loss vs. Frequency



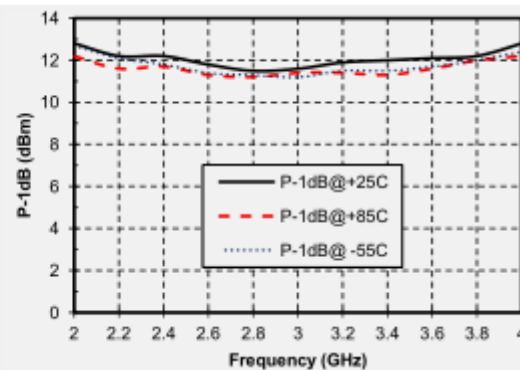
Output Return Loss vs. Frequency



Reverse Isolation vs. Frequency

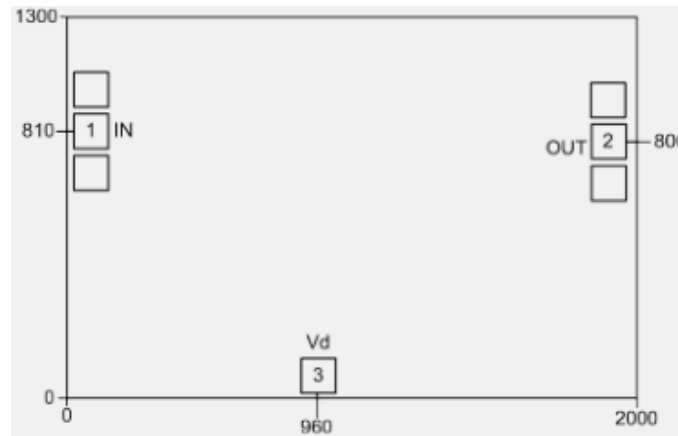


P1dB vs. Temperature





Outline Drawing:
All Dimensions in μm

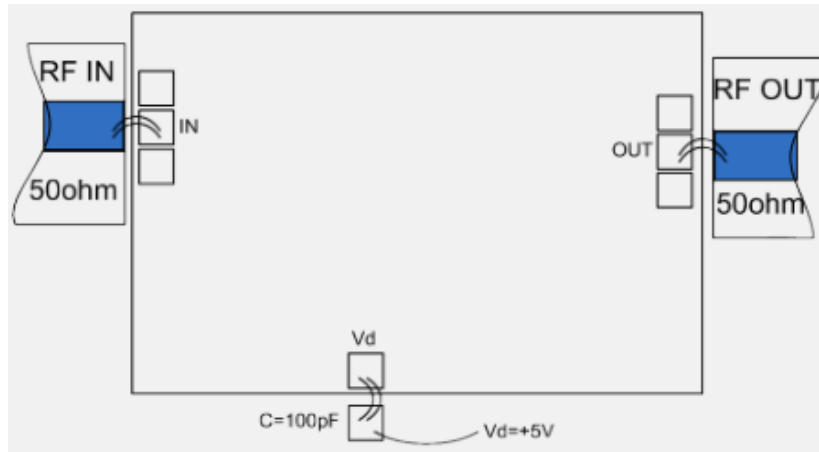


Pad Description

Pad	Function	Description	Equivalent Circuit
1	RF IN	RF signal input terminal, no blocking capacitor required.	
2	RF OUT	RF signal output terminal, no blocking capacitor required.	
3	VDD	Amplifier drain bias; external 100pF bypass capacitor required.	
Die bottom	GND	Die bottom must be connected to RF/DC ground.	



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum drain voltage: +7V
2. Maximum input power: +20dBm
3. Operating temperature: -55°C to +85°C
4. Storage temperature: -65°C to +150°C